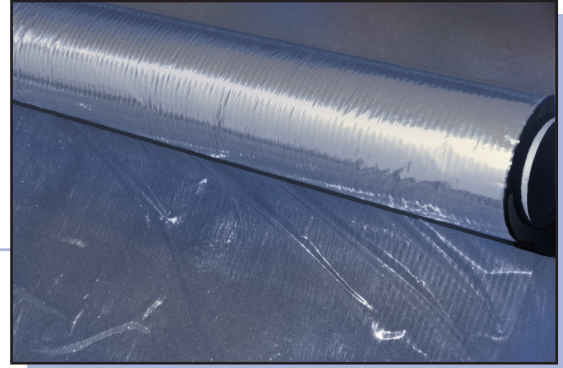


Release Films

For PCB Lamination



FEATURES

- s Allows for a clean separation from the book during the laminating processes of circuit boards.
- s Allows excellent release capability from epoxy, phenolic, polyester and other resin systems.

DESCRIPTION

Release films provide excellent release capabilities from epoxy, phenolic, polyester and other resin systems. The film can be used as a medium between the book and the platen.

Applications

- s Manufacturing of printed circuit boards during the lamination of MLB's
- s Manufacturing of flex circuit boards.

Availability

- s Thicknesses of .001 in and .002 in (.05 mm and .25 mm)
- s Perforation styles (pin pricked or punched out).

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